



**PATENT APPLICATION**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Nobuaki HASHIMOTO

Group Art Unit: 2827

Application No.: 09/720,860

Examiner: L. C. Thai

Filed: January 2, 2001

Docket No.: 108102

For: SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURE  
THEREOF, CIRCUIT BOARD AND ELECTRONIC INSTRUMENT

**SUPPLEMENTAL AMENDMENT UNDER 37 C.F.R. §1.111**

Director of the U.S. Patent and Trademark Office  
Washington, D.C. 20231

Sir:

In further reply to the October 23, 2002 Office Action, and further to the April 8, 2003 personal interview, please amend the above-identified application as follows:

**IN THE CLAIMS:**

Please cancel claim 2 without prejudice to or disclaimer of the subject matter contained therein.

Please replace claims 1, 4 and 29 as follows:

1. (Thrice Amended) A semiconductor device comprising:
  - a semiconductor chip on which a plurality of electrodes are formed;
  - a first flexible substrate in a tape form on which a wiring pattern is formed and on which the semiconductor chip is mounted;
  - a plurality of external terminals electrically connected to the electrodes with the wiring pattern interposed; and

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